



High Speed Infrared Emitting Diodes, 940 nm, Surface Emitter Technology

VSMY2943RG

VSMY2943G



FEATURES

- Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.55
- Peak wavelength: $\lambda_p = 940 \text{ nm}$
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity: $\phi = \pm 28^\circ$
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2503X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY2943 series are infrared, 940 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR illumination

PRODUCT SUMMARY				
COMPONENT	I_e (mW/sr)	ϕ (deg)	λ_p (nm)	t_r (ns)
VSMY2943RG	35	± 28	940	10
VSMY2943G	35	± 28	940	10

Note

- Test conditions see table “Basic Characteristics“

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY2943RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMY2943G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100\text{ }\mu\text{s}$	I_{FM}	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	I_{FSM}	1	A
Power dissipation		P_V	200	mW
Junction temperature		T_j	100	$^{\circ}\text{C}$
Operating temperature range		T_{amb}	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	-40 to +100	$^{\circ}\text{C}$
Soldering temperature	Acc. figure 7, J-STD-020	T_{sd}	260	$^{\circ}\text{C}$
Thermal resistance junction/ambient	J-STD-051, soldered on PCB	R_{thJA}	250	K/W

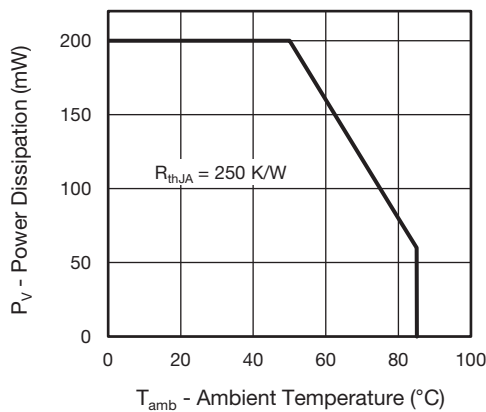


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

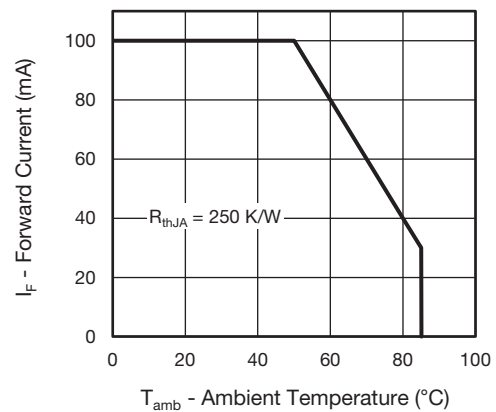


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	V_F	-	1.55	2.0	V
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	V_F	-	2.65	-	V
Temperature coefficient of V_F	$I_F = 100\text{ mA}$	TK_{VF}	-	-2.1	-	mV/K
Reverse current		I_R	not designed for reverse operation			μA
Junction capacitance	$V_R = 0\text{ V}, f = 1\text{ MHz}, E = 0\text{ mW/cm}^2$	C_J	-	125	-	pF
Radiant intensity	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	I_e	20	35	65	mW/sr
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	I_e	-	300	-	mW/sr
Radiant power	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	ϕ_e	-	55	-	mW
Temperature coefficient of radiant power	$I_F = 100\text{ mA}$	TK_{ϕ_e}	-	-0.2	-	%/K
Angle of half intensity		ϕ	-	± 28	-	deg
Peak wavelength	$I_F = 100\text{ mA}$	λ_p	920	940	960	nm
Spectral bandwidth	$I_F = 30\text{ mA}$	$\Delta\lambda$	-	40	-	nm
Temperature coefficient of λ_p	$I_F = 30\text{ mA}$	TK_{λ_p}	-	0.25	-	nm/K
Rise time	$I_F = 100\text{ mA}, 20\text{ \% to }80\text{ \%}$	t_r	-	10	-	ns
Fall time	$I_F = 100\text{ mA}, 20\text{ \% to }80\text{ \%}$	t_f	-	10	-	ns

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

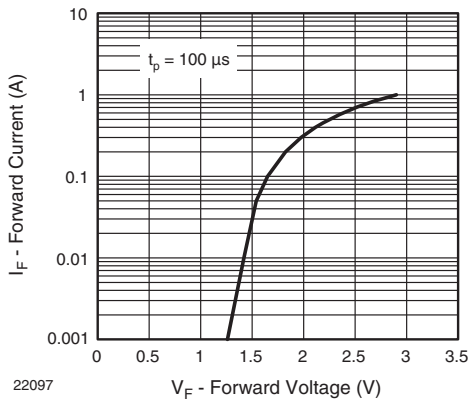


Fig. 3 - Forward Current vs. Forward Voltage

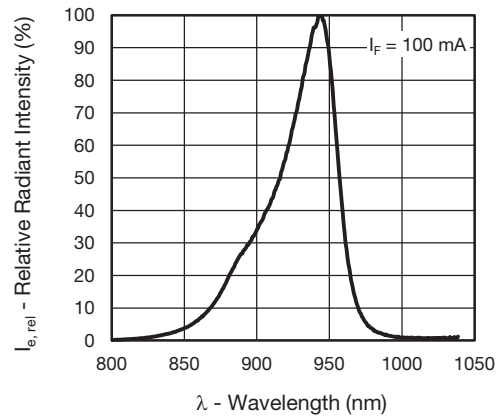


Fig. 5 - Relative Radiant Power vs. Wavelength

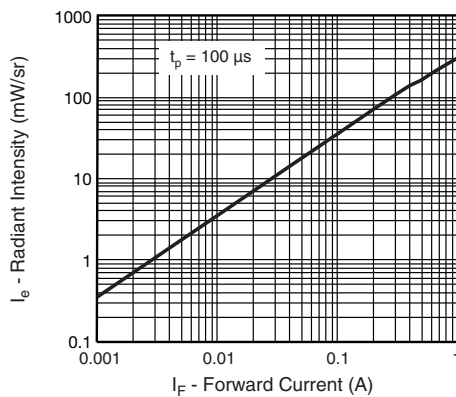


Fig. 4 - Radiant Intensity vs. Forward Current

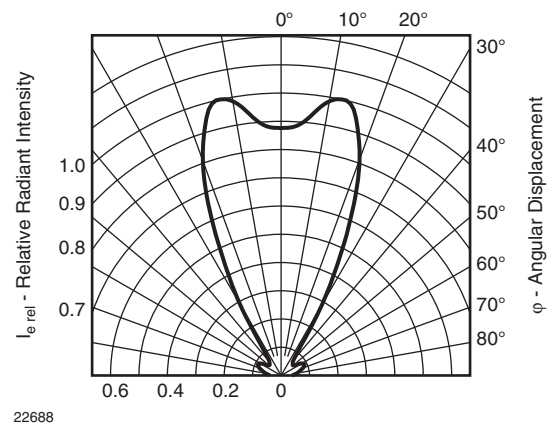


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE

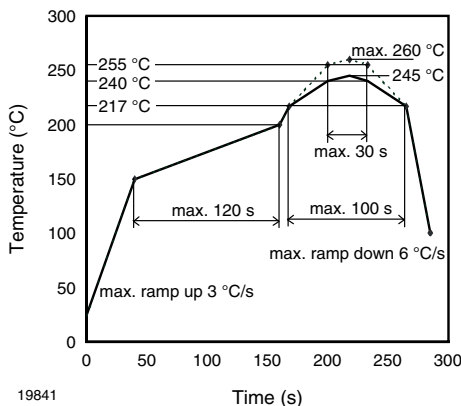


Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, RH < 60 %

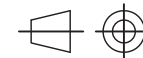
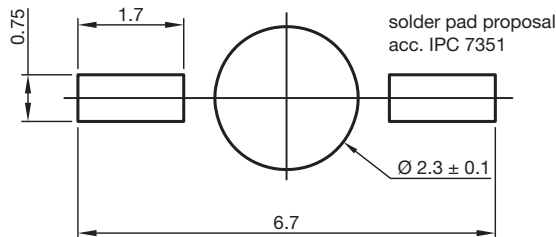
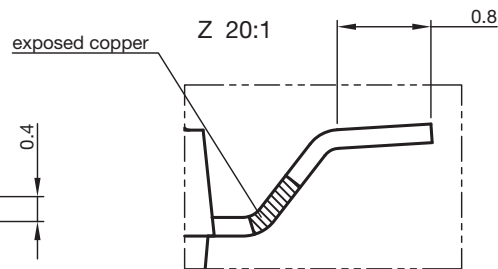
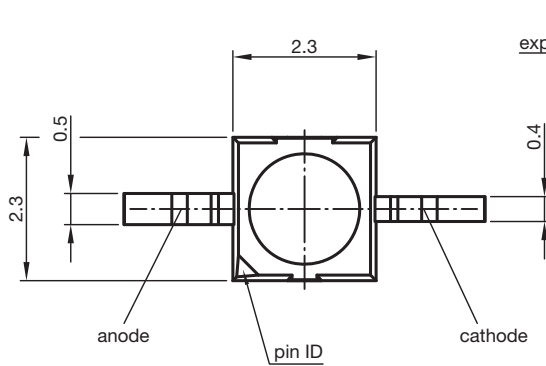
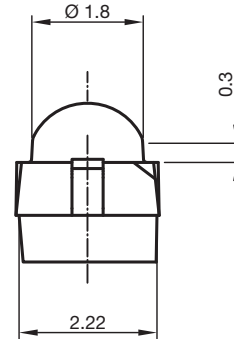
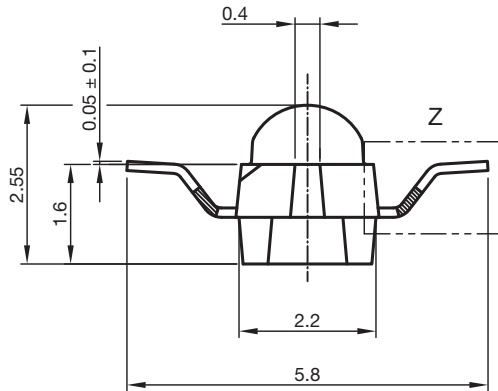
Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at $40\text{ }^{\circ}\text{C}$ (+ 5 °C), RH < 5 %.

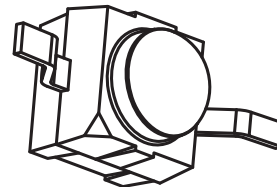


PACKAGE DIMENSIONS in millimeters: VSMY2943RG



technical drawings according to DIN specifications

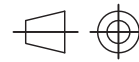
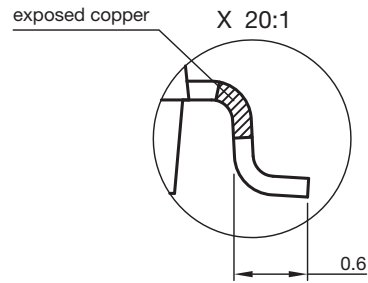
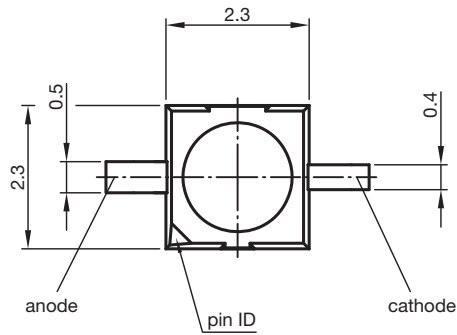
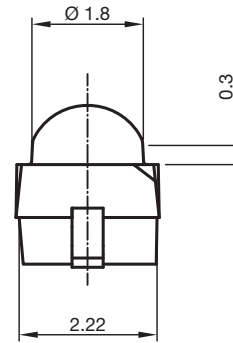
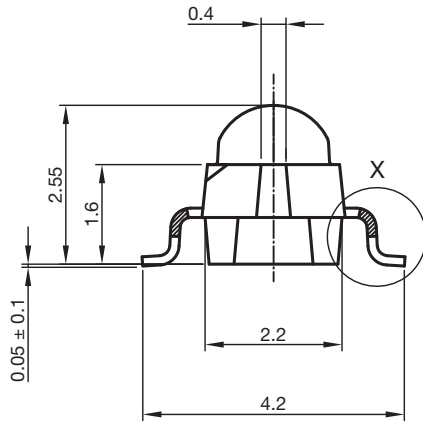
Not indicated tolerances ± 0.2



Drawing-No.: 6.544-5409.03-4
Issue: 2; 24.09.14

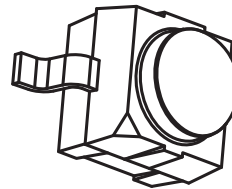
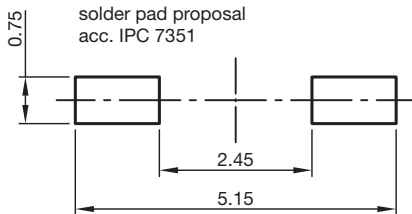


PACKAGE DIMENSIONS in millimeters: VSMY2943G



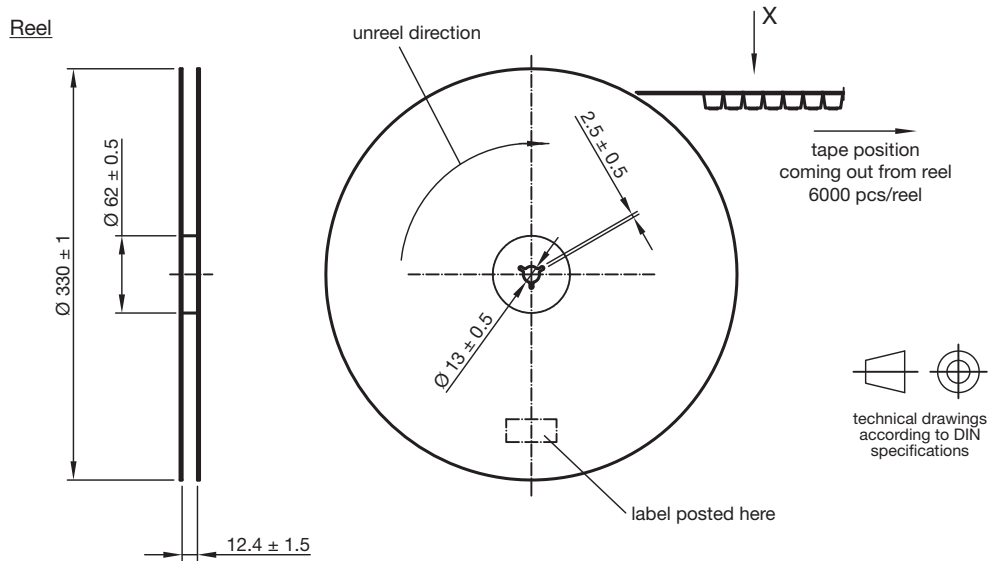
technical drawings according to DIN specifications

Not indicated tolerances ± 0.2

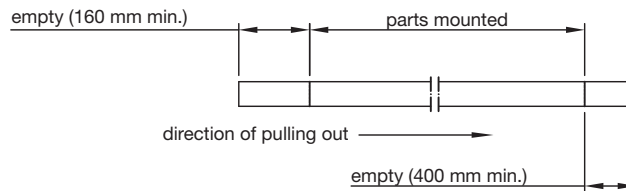


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Issue: 2; 24.09.14

TAPING AND REEL DIMENSIONS in millimeters: VSMY2943RG

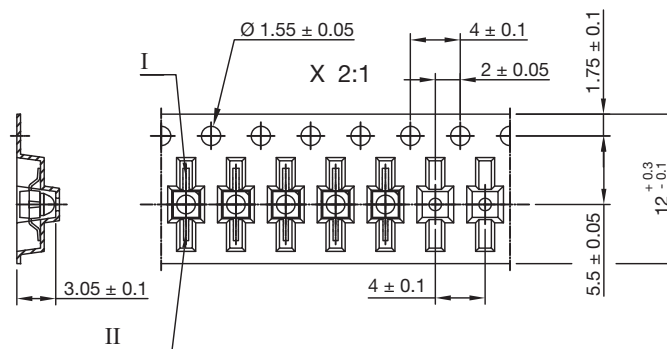


Leader and trailer tape



Terminal position in tape

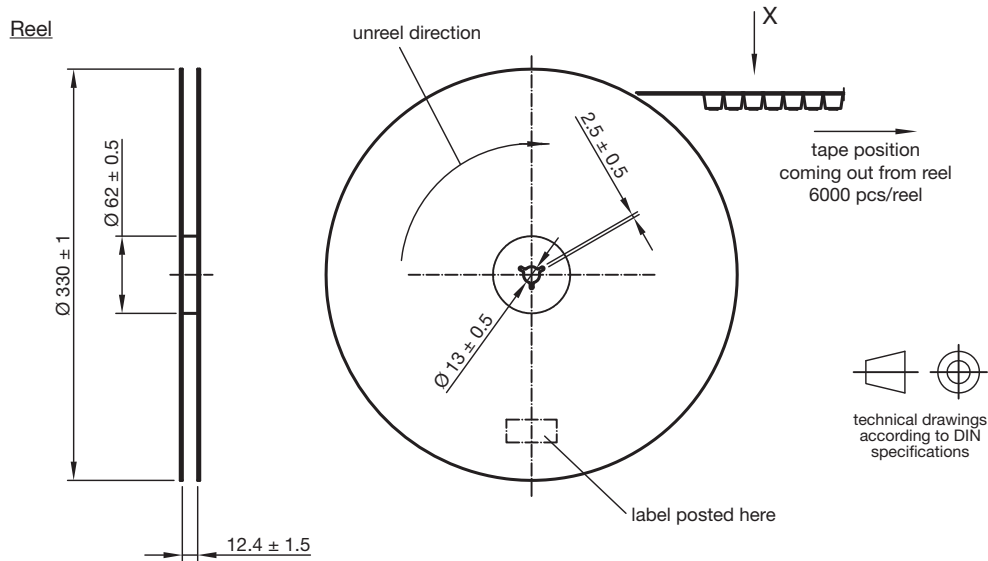
Device	Lead I	Lead II
VSMB2943RGX01	Cathode	Anode
VSMF2893RGX01		
VEMD2x03X01	Collector	Emitter
VENT2x03X01		
VSMY2853RG	Anode	Cathode
VSMY2943RG		



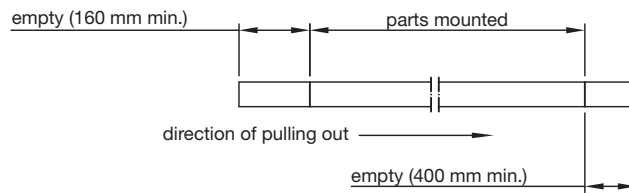
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TAPING AND REEL DIMENSIONS in millimeters: **VSMY2943G**

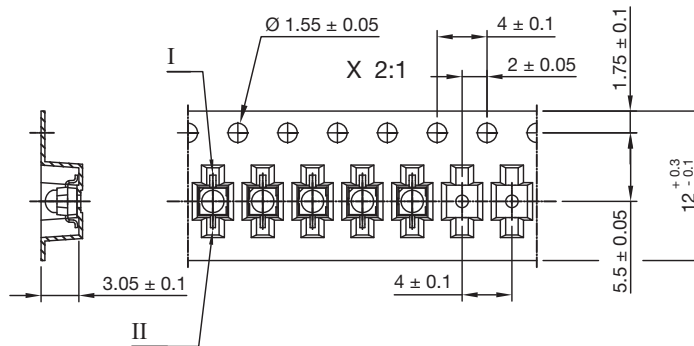


Leader and trailer tape



Terminal position in tape

Device	Lead I	Lead II
VSMB2943GX01	Cathode	Anode
VSMF2893GX01		
VEMD2x23X01	Collector	Emitter
VEMT2x23X01		
VSMY2853G	Anode	Cathode
VSMY2943G		



Drawing-No.: 9.800-5091.21-4
Issue: 2; 24.09.14



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